

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	711234	(semiconductor si silicon gaas) with (substrate carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:46
L2	187813	(bonded bonding bond) with (terminal electrode pad paddle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:47
L3	111072	(vai hole thru through opening) with (dielectric lox ((ladder adj4 oxide) adj3 (o oxide)) (ladder with (sio (silicon adj (dioxide oxide))))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:51
L4	5008	1 and 2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:51
L5	429	1 same 2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:51
L6	3032	4 and (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:51
L7	258	5 and (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:52
L8	2286	6 and (interconnect interconnecting interconnection interconnected)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/29 17:53